## 502155565 12/10/2012

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

## **CONVEYING PARTY DATA**

Name	Execution Date
Kwan-Chun Park	12/04/2012
Byeong-Kwon Kim	12/04/2012

#### **RECEIVING PARTY DATA**

Name:	STEEL LIFE CO., LTD.	
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## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13703035

# **CORRESPONDENCE DATA**

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PATENT

REEL: 029433 FRAME: 0001

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ATTORNEY DOCKET NUMBER:	5356/1
NAME OF SUBMITTER:	Mark M. Friedman
Total Attachments: 1 source=20121210095130050#page1.tif	

PATENT REEL: 029433 FRAME: 0002

#### ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, the undersigned:

Kwan-Chun PARK

Byeong-Kwon KIM

(hereinafter called the "assignor(s)"), hereby sell(s), assign(s) and transfer(s) to:

STEEL LIFE CO., LTD.

STEEL FLOWER CO., LTD.

(hereinafter called the "assignee(s)"), its/his successors, assignees, nominees or other legal representatives, the Assignor's entire right, title and interest in and to the invention entitled:

## A METHOD FOR MANUFACTURING A SHEET MOLDED TO FORM A MULTI-DIMENSIONAL CURVED SURFACE

described and claimed in the following patent applications:

U.S. Patent Application identified as Atforney Docket No. (5356/1) and executed the same date as this assignment;

and in and to said Patent Applications, and all original and reissued Patents granted therefor, and all divisions and continuations thereof, including the right to apply and obtain Patents in all other countries, the priority rights under International Conventions, and the Letters Patent which may be granted thereon;

Signed and scaled this \( \frac{1}{2} \) day of \( \frac{1}{2} \) day of \( \frac{1}{2} \)

X C POYK

Byeong-Kwon KIM

PATENT REEL: 029433 FRAME: 0003

**RECORDED: 12/10/2012**